

### DESCRIPTION

The SD8Dxxx Series is designed for applications requiring transient overvoltage protection capability. They are intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment and other applications. These devices are ideal for situations where board space is at a premium.

This series has been specifically designed to protect sensitive components which are connected to power, data and transmission lines from overvoltage caused by ESD(electrostatic discharge), CDE (Cable Discharge Events),and EFT (electrical fast transients).

### ORDERING INFORMATION

- ✧ Device: SD8Dxxx
- ✧ Package: DFN1006
- ✧ Material: RoHS compliant & Halogen free
- ✧ Packing: Tape & Reel
- ✧ Quantity per reel: 10,000pcs

### FEATURES

- ✧ IEC61000-4-2 (ESD)  $\pm 30\text{kV}$  (Contact)  
 $\pm 30\text{kV}$  (Air)
- ✧ IEC61000-4-4 (EFT) 40A (5/50ns)
- ✧ Protects one I/O line (unidirectional)
- ✧ Low clamping voltage
- ✧ Working voltages: 3.3V to 36V
- ✧ Low leakage current

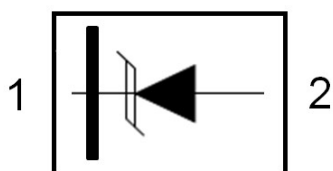
### MECHANICAL DATA

- ✧ DFN1006 package
- ✧ Flammability Rating: UL 94V-0
- ✧ Packaging: Tape and Reel
- ✧ High temperature soldering guaranteed:  
260°C/10s
- ✧ Reel size: 7 inch

### APPLICATIONS

- ✧ Cell Phone Handsets and Accessories
- ✧ Microprocessor based equipment
- ✧ Personal Digital Assistants (PDA's)
- ✧ Notebooks, Desktops, and Servers
- ✧ Portable Instrumentation
- ✧ Networking and Telecom
- ✧ Serial and Parallel Ports
- ✧ Peripherals

### PIN CONFIGURATION



### PACKAGE OUTLINE



## ABSOLUTE MAXIMUM RATING

| Symbol    | Parameter                                                      | Value                | Units |
|-----------|----------------------------------------------------------------|----------------------|-------|
| $V_{ESD}$ | ESD per IEC 61000-4-2 (Contact)<br>ESD per IEC 61000-4-2 (Air) | $\pm 30$<br>$\pm 30$ | kV    |
| $T_{OPT}$ | Operating Temperature                                          | -55/+150             | °C    |
| $T_{STG}$ | Storage Temperature                                            | -55/+150             | °C    |
| $T_L$     | Lead Soldering Temperature                                     | 260 (10 sec.)        | °C    |

## ELECTRICAL CHARACTERISTICS ( $T_{amb}=25^{\circ}C$ )

| PART<br>NUMBER | DEVICE<br>MARKING | V <sub>RWM</sub><br>(V)<br>Max | V <sub>B</sub><br>(V)<br>Min | I <sub>T</sub><br>(mA) | V <sub>C@1A</sub><br>(V)<br>Max | V <sub>C</sub><br>(V)<br>Max (mA) |    | I <sub>R</sub><br>(μA)<br>Max | P <sub>pk</sub><br>(W)<br>Max | C <sub>T</sub><br>(pF)<br>Max |
|----------------|-------------------|--------------------------------|------------------------------|------------------------|---------------------------------|-----------------------------------|----|-------------------------------|-------------------------------|-------------------------------|
| SD8D3V3        | 03W               | 3.3                            | 4                            | 1                      | 6.5                             | 16.0                              | 32 | 5                             | 512                           | 450                           |
| SD8D5V0        | 05W               | 5                              | 6                            | 1                      | 9.8                             | 18.5                              | 27 | 2                             | 500                           | 300                           |
| SD8D8V0        | 08W               | 8                              | 8.5                          | 1                      | 10.5                            | 20                                | 23 | 1                             | 460                           | 240                           |
| SD8D12V        | 12W               | 12                             | 13.3                         | 1                      | 19                              | 28                                | 14 | 1                             | 392                           | 130                           |
| SD8D15V        | 15W               | 15                             | 16.7                         | 1                      | 24                              | 32                                | 12 | 1                             | 384                           | 120                           |
| SD8D18V        | 18W               | 18                             | 20.0                         | 1                      | 29                              | 35                                | 10 | 1                             | 350                           | 100                           |
| SD8D24V        | 24W               | 24                             | 26.7                         | 1                      | 43                              | 45                                | 8  | 1                             | 360                           | 80                            |
| SD8D36V        | 36W               | 36                             | 40                           | 1                      | 60                              | 73                                | 5  | 1                             | 365                           | 60                            |

## ELECTRICAL CHARACTERISTICS CURVE

Fig 1 8/20 $\mu$ s Waveform per IEC61000-4-5

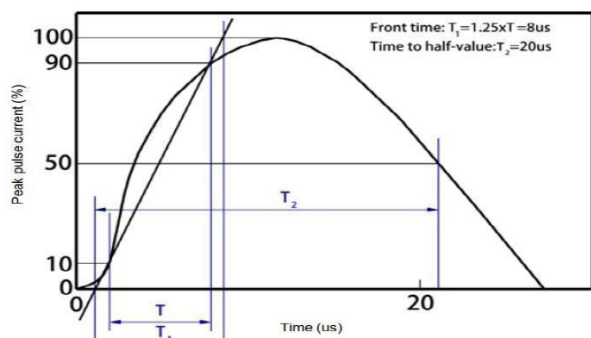


Fig 2 Contact Discharge Current Waveform per IEC 61000-4-2)

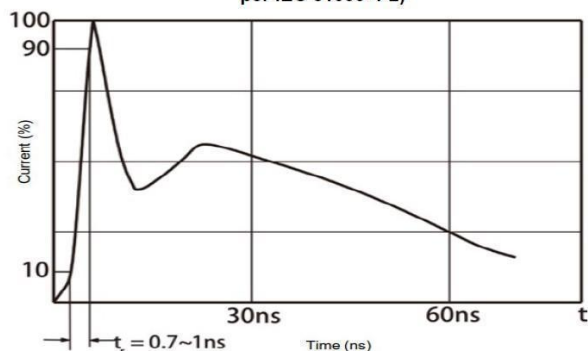


Fig 3 Voltage vs Capacitance

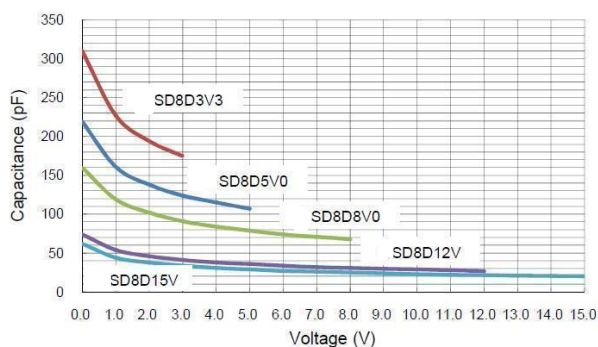


Fig 4 Voltage vs Capacitance

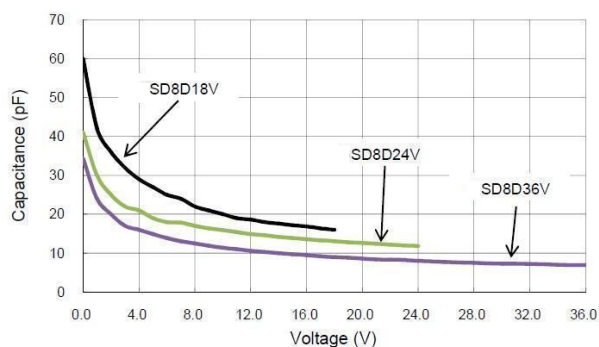


Fig 5 Clamping Voltage vs Peak Pulse Current

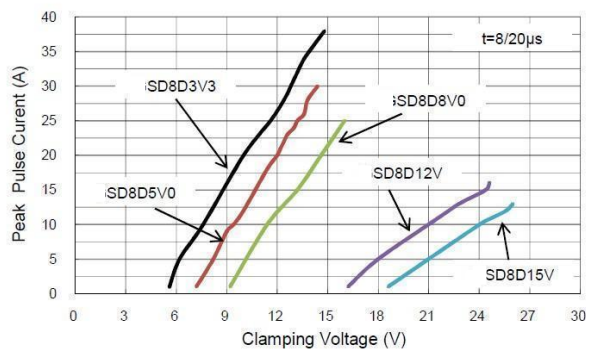
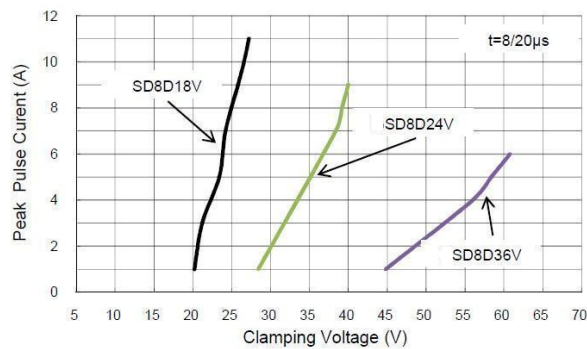
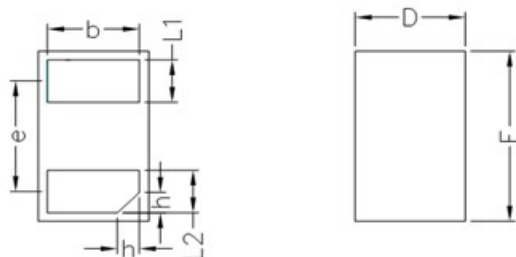


Fig 6 Clamping Voltage vs Peak Pulse Current



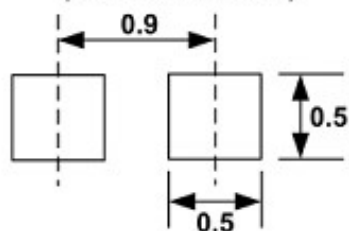
## DFN1006 PACKAGE OUTLINE DIMENSIONS



Unit: mm

|    | MIN     | NOM  | MAX  |
|----|---------|------|------|
| D  | 0.55    | 0.60 | 0.65 |
| E  | 0.95    | 1.00 | 1.05 |
| L1 | 0.20    | 0.25 | 0.30 |
| L2 | 0.20    | 0.25 | 0.30 |
| b  | 0.45    | 0.50 | 0.55 |
| e  | 0.65BSC |      |      |
| A  | 0.45    | 0.50 | 0.55 |
| h  | 0.07    | 0.12 | 0.17 |

Dimension: Millimeter  
( Stencil thickness: 0.1 )



**Soldering Footprint**